

資訊科學與工程研究所

Adaptive Prefetching Techniques and Latency Overlapping

Scheduling for 3D Wide I/O Memory

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Adaptive Prefetching Techniques and Latency Overlapping Scheduling for 3D

Wide I/O Memory

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調適提前讀取技術與重疊延遲排程之三

維寬頻記憶體

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摘 要

隨著記憶體與中央處理器存取速度的差距,記憶體已經成為系統效能的瓶頸,提 升記憶體存取速度將有助於改善系統效能,由於近來 TSV 技術的成熟,晶片將可以用 堆疊的方式來減少存取延遲時間。然而當系統晶片整合朝向三維發展,設計將會更複 雜且效能更難被評估。

本篇研究我們實作一個三維記憶體模擬平台並且支援 JEDEC 寬頻記憶體傳輸介面 來評估系統效能。 同時模擬器支援多執行緒平行處理來加快模擬時間。藉由分析寬 頻記憶體的特性,我們提出了兩個機制來提升三維架構下的記憶體效能,調適提前讀 取技術藉由分析記憶體區塊的存取密集程度及狀態並且參考指令列隊的數量來進行 提前讀取,並且提高堆疊層間的平行度。重疊延遲排程則是利用 TSV 傳輸延遲來提前 執行充電指令,達到重疊延遲時間。

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ABSTRACT

Due to the gap between memory and CPU speed, memory has become a bottleneck in computing systems. Improving memory access latency will improve system performance. As TSV technology matures, chips stacked in different stratums can reduce access latency. However, as SoC development moves towards 3D, it becomes increasingly difficult to evaluate complex systems designs.

In this thesis an ESL platform is implemented which can support JEDEC wide I/O interface to evaluate memory performance. The simulator supports multi-threaded modeling and speedups the simulation time. After analyzing address mapping methods and properties of wide I/O, this thesis proposes two mechanisms to improve the performance of 3D architecture. Adaptive-prefetching will analyze memory intensive blocks and reference command queue status to prefetch data and improve RLP. Latency overlapping scheduling executes precharge command by beforehand analyzing TSV bus utilizaion.

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I. Introduction

1.1 Motivation and Introduction

Memory System is one of the most important in computer architecture, but the speed of memory access is improving much slower than CPU. The gap of memory and CPU speed is called "Memory Wall" and it has been a system bottleneck for two decades. One of the reasons is due to the different between memory and logic IC fabrication process. DRAM is made by high-density NMOS transistors which emphasize on capacity or leakage power. On the other hand, processors use CMOS transistors and optimize for performance. The difference means that logic layer and DRAM layer can't coexist because IC fabrication process constraints.

Recently, memory bandwidth demands and chip size are still increasing since multicore era. The new technology called "TSV" may solve this problem. With the advancement of technology, 3D SoC integration can stack multiple stratums of chips and breaks area and pin count constraints. It also brings other advantage such as lower latency and more power efficiency. Although 3D stacked memory is more powerful than traditional designs, it's hard to evaluate the complex SoC design. In order to analyze performance of this new technology, building an accuracy model to simulate and provide some information for the 3D stacking technology in the early stage is necessary. Using a platform which is built by high level language to evaluate the system performance is a common way for large complex

design and this flow is generally called ESL**[1][2]**.

Logic layer is designed to be at the bottom stack of the stacked chip architecture for mobile wide-I/O DRAM, as shown by Kim**[3]**. Traditional memory is constrained by the specifics of processors and is hard to improve performance. Memory controller design can be more complex and separates from processor side to memory logic layer. One of the advantage is the memory controller can be optimized by its own memory manufacturers. Figure 1 show the design of 3D stacked memory. There are some issues that need to be addressed in order to improve memory performance in wide I/O.

First, balance resource's utilization by analyzing memory address mapping. Address mapping affects the banks or ranks usage. It is hard to decide optimized mapping method for different memory systems because diverse memory hardware constrains and distinct properties. This work explores wide I/O property with different mapping method by traces analysis.

Second, prefetching mechanism can help to reduce memory access latency. It is

difficult for prefetcher to get memory state information traditionally because it is designed close to CPU. With 3D SoC integration, memory controllers can combine more complex logic design. This thesis proposes adaptive prefetching technique by analyzing memory block intensively and the possibility of continuous adjacent addresses. In order to reduce useless prefetch requests, this work further use a set of counters to observe the command queue state and improve memory rank level parallelism.

Third, open-page row buffer policy is widely used because most programs have spatial locality when access memory. DRAM controller will issue precharge command to close row buffers until other command use other rows in the same bank. It may waste power if the row buffer is not used more efficiently. Moreover, TSV data bus is shared by each rank and transfers data with burst length mode. The following data commands have to wait for the transmission complete. This thesis try to pre-issue precharge command when TSV bus is busy and overlapping the latency.

Finally, discuss the extra hardware cost in our experiment.

1.2 Contribution

1 Provide an ESL platform that can model Wide I/O interface. It can help to evaluate 3D IC integration development in the early-stage.

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- 2 Using pthread to speed up simulation time.
- 3 Analyze the address mapping method and property of wide I/O interface.
- 4 Provide two mechanism: Adaptive prefetching techniques and latency overlapping scheduling to improve system performance.

1.3 Report Organization

The remainder of this thesis' structure is as follow. Section II introduces the background of DRAM and the policies to improve system performance like prefetching or predict precharge. Section III describes the framework of our 3D DRAM simulator. Section IV describes the scheduler and policy to hide latency policy in order to improve the DRAM access latency. Section V introduces our experiment environment. The result and cost are also taken into consideration. Finally this thesis compares our method with others and evaluates the advantage and disadvantage.

II. Background and Related Work

TSV technology is the trend of future design. This chapter will briefly describe some basic concepts of DRAM property and 3D wide I/O interface backgrounds. Next, this work introduces previous works that utilize prefetching and scheduling method to improve DRAM performance. Finally, we will present a table of analysis advantage and drawback analysis on those control method in 3D IC era.

2.1.1 Row Buffer

Row buffer is like a cache of bank arrays. It is a very important component in the DRAM system because every access will go through this buffer and transfer by amplifier to enlarge the signal. Figure 2 shows a typical row buffer design. Upon memory access, the entire row of DRAM bank is amplified by a sense amplifier before loading into row buffer and in the process, the row data in DRAM is destroyed. This action is called "ACTIVATE". After the row buffer is activated, the following row access is related to the row buffer. Because activate is a destructive access, data must be restored into DRAM before another row is used. The restore action is called "PRECHARGE". The maximum number of activated row buffers is limit per rank. For example, DDR2 and DDR3 use FAW(Four activated windows), but Wide I/O uses TAW(Two activated windows). Activated command also has a timing constraint for issuing called "tRRD". The timing diagrams show the

relationship to each operation. "tRCD" is the minimum time interval that can issue memory access command after the activated action. "tCL" is the minimum timing interval between memory access command and data put into the data bus. "tRP" is the minimum timing interval between recharge. "tRCD", "tRP", and "tCL" are the most frequently discussed timing parameter in memory systems.

2.1.2 Row Buffer Page Policy

While the memory is accessing data, there are three common timing parameters: precharge, activated, and access column. If the row being accessed is currently opened, it can directly access data without precharging or activating the row. These three primary row buffer page policies are open page policy, closed page policy and timing policy.

Open Page Row Buffer Policy

Open page policy will keep opening and holding a row of data. The policy is good

for data with spatially locality because the row buffers do not have to be activated twice in a period. If the access commands are mapped to the same opening row, it can directly access the DRAM data without other commands. And it will issue PRECHARGE command until a new command accesses a different row. The open page policy is widely used in general-purpose computer.

Close Page Row Buffer Policy

Close page policy will close the row buffer as soon as the command access is completed. It will take advantage of random memory access because it may save precharge time. If the rate of row buffer hit is low, close page policy may be better than open page policy.

Timeout Policy

Timeout policy will close the opening row after a time interval. This policy will provide tradeoff between open and close page policy.

THE **2.1.3 Memory System**

Recently the DRAM system has one or more channel controllers design. Each controller controls a separate portion of the memory system. Because of the command and data bus are also duplicated, each controller can issue command or access data concurrently without any dependency.

The basic DRAM system consists of one or more ranks. Each rank has many Banks and shares the same command and data bus. When the data have to access across the rank, the system must delay command and pay the rank to rank switch time penalty.

Bank is the basic component of the DRAM system just like a two dimension data array which is composed by many bit cells. Because each bank in the same rank can work concurrently, it can hide the latency if multiple banks are activated and accessed data in parallel. Each bank has a row buffer and the data access must go through the row buffer.

2.1.4 TSV Technology

TSV is abbreviated from Through-Silicon-Via. The new technology lay chips stack by stack 3 dimensionally. The delay of TSV is also shorter than tradition horizontal bus. Memory can be stacked as a cube then add a new dimension call layer. The delay is directly proportional to the distance from controller to the layer.

Wide I/O is based on the TSV technology to control data transfer of the stacked memory. The feature of this device is it can stack up to four layers of memory. There are four channel controllers in the Wide I/O interface, and each controller controls section of the memory stack independently. The data bus is 128 bits wide. The total memory size can be up to in 32 Gb in density. The voltage is only 1.2V and the frequency is 200MHz. Each layer is an independent system, so the timing constraint is different from transition design. For example, DRAM system can issue access commands to different rank in succession in a 3D memory system, but traditionally the timing delay constraint is exists which is call Rank to Rank Switch time. Previous researches **[4][5][6]** analysis of TSV shows that 3D integration technology will impact not only memory stacks, CPU caches and cores may also

need to be re-designed.

Figure 4 TSV Technology

2.2 Memory Controller Scheduling

Scheduling policy plays an important role in the Memory system. Because of the destructive access control in DRAM, the access ordering will impact numbers of precharge and activate new row into row buffer. Unsuitable access ordering will cause power consumption and longer access latency. There are many researches about reorder the command requests to improve the system performance. Different polices optimizes the scheduler to adapt to a particular property. A good scheduling will improve the DRAM bandwidth and delay. In this section, this thesis will introduce some state-of-the-art scheduling policy about DRAM.

2.2.1 FR-FCFS Schedule

Because DRAM access pays less latency penalty when accessing already opened rows, read latency can be significantly reduce with more page hits. Rixner proposed a scheduling policy which is called "First Ready-First Come First Serve"**[7]** and it is the common policy in today's memory system. This scheduler will reduce latency as the following timing diagram. FR-FCFS issues commands to already opened row buffer over other requests. It is just like a greedy algorithm scheduling policy for improving row buffer hit ratio. If there are no opening requests that can be issued now, the scheduler will prioritizes and issue oldest request just like FCFS scheduling policy.

Figure 5 FR-FCFS Command Scheduling

2.2.2 Fairness Scheduling

Because FR-FCFS scheduling policy is a greedy algorithm, it may cause starvation when some requests are continuously served in the period. A memory intensive program will send a lot of memory requests to DRAM and be issued quickly because the possibility of those rows being opened is higher than other request. Other requests will delay for a long time and programs will be stall because the data is not return from memory. Some researches take requests waiting time into consideration and adjust the controller's request priority periodically. For example, the scheduler can give basic priority number for requests and increase it after a time interval. This action gives higher priority to the older requests, thus the read request delay times are more balance. The priority aging**[8]** concept will reduce the unfairness situation for solving starvation and it is important since it affects the CPU waiting time. There is a tradeoff between performance and fairness because it breaks the continuous row buffer access times for fairness scheduling. Memory timing constraints should also be taken into considers. Virtual writing queue**[9]** reduces memory read to write delay penalty. By handling write command separate from read, this mechanism helps to issue continuously read and minimalize read to write delay in overall memory system.

Thread status can also issue to the memory scheduling, because of shared cache replacement and data bus, many resource may cause contentions. ATLAS**[10]** is a memory scheduling algorithm that improves system throughput by prioritizing threads that have smaller attained memory service. Those threads may more likely be memory non-intensive and improve performance significantly by serving those threads' request soon. PAR-BS**[11]** focuses on thread fairness and prevent short term and long term starvation by taking registers info per request and thread ranking. Although there are many method to improve memory performance, most of them have to bypass some information from CPU to memory controller and the design must also be constrained.

2.2.3 Scheduling Summary

Table 1 Comparison of Scheduling

Many scheduling are based on FR-FCFS policy to improve performance, and pass information from CPU by adding extra cache tag. This method will increase bus communication traffic and hardware overhead. In this work, we use a prediction table to issue precharge command early and overlap the bus transmission time.

2.3 Prefetch Policy

Prefetching mechanism can predict the next address and fetch data beforehand. Stream prefetcher can keep track of multiple access streams. "Prefetch Distance" and "Prefetch Degree" determine the aggressiveness of the prefetcher. Aggressive prefetching mechanism can improves performance, but miss fetch in some benchmark decreases system performance.

In order to reduce the miss predict ratio some papers proposes to analyze the feedback information and adjust the prefetcher dynamically. Feedback Directed Prefetching**[12]** provides three factors to control prefetcher's behavior: "Prefetch Accuracy", "Prefetch Lateness", and "Cache Pollution" as show in Table 3.

Table 2 FDP Control Table

As soon as the prefetching data returns, it will update the information and determine whether to use prefetcher or not. These prefetchers are often incorporated in cores and observe program behavior to predict whether to prefetch data or not. In order to keep track of the prefetch requests, the Last Level Cache has to add the entry to identify the demand requests and prefetching requests. It is an overhead in overall architecture and does not fit the DRAM property. Coordinated control **[13]** solves the problem about inter-core prefetch requests conflict in cache. Prefetcher causes inter-core interference and may diminish prefetching's potential performance. In order to reduce conflict, it adds an extra center controller to manage which prefetch requests can be sent into memory system. Lee et al.**[14]** combines the prefetcher and memory architecture to improve bank level parallelism. Bank is the basic component of the memory system, each bank can work independently. The concept of bank level parallelism is to overlap delay by access bank concurrently. BLP-Aware Prefetch Issue will keep track of which bank the prefetching requests will be issued to and issue them out of order to improve the bank utilization. Furthermore, BLP-Preserving Multi-core Request Issue Policy also considers the prefetching requests from multi-core. It controls the order of prefetching requests and issues those from the same core first. This mechanism minimizes the destructive interference in the BLP of each program.

The general priority schedulers that deals with prefetch requests can be put into two categories, one type of prefetching request schedulers**[15–17]** gives less priority to prefetching requests than normal request. Since the prefetcher is assigned lower priority, the normal request will be issued faster than the predicted prefetching requests. It will drop the prefetching request if the prefetching requests waiting time is too long, as it is more likely te be a useless demand. The other policy**[18]** treats prefetching requests as a demand request. So it will schedule equally and fairly performance if the prefetcher prediction hit rate is high.

2.3.1 Comparison of Prefetch Mechanism

Table 3 Comparison of Prefetching

Many prefetchers access data and dynamic adaptive current state. There are some extra components to record precise and pass into memory controller. In this work, we use a table record memory intensive block and prefetch data will improve latency with low hardware **THEFT** cost overhead.

III. 3DRAMSim Framework

3.1 Overview

This section describes the feature of our 3DRAMSim simulator. 3DRAMsim is a DRAM cycle accurate simulator which is based on DRAMSim2**[19]**. Our simulator can provide 3D memory environment to analyze design in an early-stage. In our simulator, we also can simulate traditional DRAM like SDRAM or DDR memory from JEDEC protocols. Our simulator can easily model different type of memory by modify the system configuration files and timing parameters. All DRAM properties are parameterized and described in the memory configure file. With the development of TSV technology, system can also control different layer independently and share the same data TSV bus. Our simulator can also model multi-channel architecture and concurrently operate of DRAM.

Figure 6 Program Execution Flow

Figure 6 illustrates the 3DRAMSim flow diagram. The proposed simulator includes three parts: trace splitter, memory controller, and memory storage. The trace splitting stage includes overall system timing control, and address mapping analysis tool. In order to simulate the multi-channel environment, trace must be pre-process, split into sub-traces and issued by each channel controller. Trace splitting has to know the address mapping method and separate requests mapping into their sub-trace. After the trace splitter, each controller increases their own timing domain count. If this counter is less than the trace's timestamp, the trace will issue until the counter equal to the timestamp and another request will not be issued in the same channel. After all trace are finish, system will show those information and physical execute time to help us evaluate our design.

3.2 Parameter Design

Many specifics described as parameters, can improve program flexibility and usability. It can simulate other memory architecture by modifying some critical property with low overhead. There are two classic configurations for our simulator.

First, memory configuration file will provide the timing and current parameter. It also gives the architecture structure information for DRAM like number of banks and ranks.

Second, system configuration file provides the policies for our target DRAM. These policies include row buffer policy, memory address mapping, and scheduling method. With many policies, we have to modularize respective functions to make the program more readable and easy to expand.

Finally, we use indirect pointer to link the function section in the initial time to save the comparison time in each simulation cycle. After the pointer is built successfully, we can use this pointer to call specific function directly. It can easily switch to other policies without recompilation of the program, making it more efficiency.

3.3 Channel Controller

BankState is a table that describe the current bank state including current row buffer state, current command issued, and requests action corresponding to reasonable cycle time to fit the timing constrain. This state table will determine when the command can be issued or not in this cycle and update the table state whenever a command is committed.

Channel controller is the main control of the memory system and operates disjointed portions of memory stack independently. Command queues store those memory requests scheduled by the scheduler in the buffers. Commands sequence will be reordered and issued out of order to improve the memory performance. In our 3DRAMsim simulator, this work provides the well-know FR-FCFS scheduling policy.

Each controller access a portion of the memory stack. They do not cause interference and the clocks are maintained by its own domain. The timing clock is store in the controller object and increases every time controller update called by the upper system. As soon as the timer increases, next cycle will come and schedulers compare the bank state timing constraint with the current clock to schedule those commands.

3.3.1 TSV Modeling

All ranks are shared by the same TSV bus in region of the same channel controller. The signal can be classified into two kinds: control signal and data bus. The total numbers of TSV is 300 in wide I/O interface for each controller. Controller can continuously send a command to different ranks every cycle if the command conforms to the timing constrain.

Because wide I/O is burst oriented, all the data accesses are uses burst mode to transfer. The data bus must be locked a period by data burst transfer with many cycles. In wide I/O interface, the burst length is either two or four cycles. Also, the stacked memory property only restricts each timing constraint in the current rank. In other word, the data commands may be sent continuously. The data bus competed by controllers, so it must have an arbiter to determine which one can use TSV data bus in this period and when to release the resource. There is a counter in our wide I/O bus model. It will add burst length to reflect the bus transfer when the arbiter decides which controller has the next period. Memory controller will call the lock function to prevent different ranks using the TSV bus when transaction is not complete. After TSV data bus is locked, the counter will count down to zero and then unlock the data bus. If the bus is free, the controller will select the earliest command for scheduling and lock the data bus. It will simulate command continuously and access data sequentially to transfer. Our TSV bus modeling can more accurately describe data bus utilization. Simulator can also reflect the bandwidth by calculating the locking cycle. It is an important metric for memory intensive programs.

In order to save power, it can switch to low power mode if the command queue is empty and the state is idle for a rank. If there are other commands injected into the command queue, the rank will switch to normal mode after in a period. It can calculate the activate time in the power up cycle to reflect utilization for each rank.

3.4 Accelerating Simulation

In recent development, DRAM has more and more ranks and controllers to improve access latency. With the simulation components increasing, simulation time also become much longer because each object has to update its state or transfer data every cycle in the simulator. Some of them are unnecessary updates only check and increase cycle when the command queue is empty. There are many potential opportunities to speed up the DRAM simulator. For example, the previously mentioned indirect pointer saves unnecessary comparison time when program executes. Also, it can find and improve program parallelism issues to speed up simulation time. Our speedup mechanism in the 3DRAMsim focuses on channel controllers because the control, data, and clock signals are critical to independent control. It means different channel controllers can be executed on their own and the executions are likely to be parallelized. Furthermore, the result of the speedup version must be the same as original version to prove the correctness. In order to speed up the channel controllers, this work has to modify the program execute about the channel update function. The original version updates channel use loop and update sequentially whenever system cycle increase and the ordering will not be affected because the controllers are independent.

If the system only has one trace for simulator, it is hard to reflect concurrent execution for a multi-channel architecture. The trace splitter is described in the previous section. After the memory system is created, it also creates many threads for each channel controller in our simulator. Figure 7 show the concept of the thread creation for each channel. In our multi-thread version, each thread updates their own ranks partially without dependency. The simulation cycle is the maximum cycles in all the sub-trace returned from the trace splitter. Because of threads' difference in speed, it has to wait for all controller threads to finish its job, so there is a synchronous point to check for whether other controllers are completed or not. The program will insert a barrier to wait for the slower job and print all the information after all controllers simulate completed. The result in both versions must match to verify the speedup version's correctness.

Figure 8 show our simulator speeds up 3.1 times compare to sequential version in average. Considering threads diversity, some threads have to wait for the slowest one, the degree of speedup is always nearly the number of threads if host machine has enough cores and can support threads to execute independently. The maximum speedup will be proportional to the number of channels and the upper bound is four times in wide I/O interface.

Figure 8 Simulation Speedup Times

3.5 Profile Model

With the TSV technology coming, there are some differences from traditional DRAM memory system. Controllers can issue different command to every rank by interleaving. The rank can issue commands only when sharing the same data bus. The timing constraint in different ranks only have to consider their layer inside. The property of the parallelism factor will also be different because the ranks behavior also changes. For example, the rank to rank switch time will impact the rank level parallelism and the activated row buffer constraint will impact bank level parallelism. There are more complex factors for 3D IC development, and the best addressing mapping policy will become harder to find. Our simulator provides some simple methods that can find a better mapping method to fit your demand. Better mapping methods can be found by two steps. After mapping analysis, the simulator will find the trend of different mappings for the current architecture.

First step of evaluation is focused on the rank and channel utilization in the memory system. The delay becomes longer because the parallelism factors decrease. If ranks or channels mapping are unbalanced, it will cause some resource to idle, causing violent competition in some rank. This step will eliminate the most of the impossible mapping methods, but some case is hard to find because the number of commands will continued to increase in disperse ranks for a long time.

Second, memory level analysis is important to mapping performance. It will run 3DRAMsim with trace by without timestamp. This step will show parallelism because the command dependency will be roughly taken into consideration. The simulation time is faster than the complete simulation because it does not have to wait for the trace interval for command issues. This work chooses those potential methods as candidates and analyze artificially. The traditional mapping methods consider the bank level parallelism and column access locality in the simple memory system.

The results show mapping channel's bits to lowest bits is better because when mapped to upper bits, the bits are more unbalanced and have less channel level parallelism, since having independent channel controllers achieves the maximum parallelism. Moreover, the row bits are mapped to higher bits because this way there is no parallelism issue between each row. If the row bits are mapped to the lower bits, it may more likely use a different row and cause more penalty for row buffer switch.

IV. Control Mechanism

4.1 Address Mapping Analysis

Semi-automatic method can eliminate those low performance combination mapping. It shows the row bits mapping to high and channel bits mapping to low get better performance for wide I/O interface. This thesis analyzes the other parallelism issue to fit the 3D architecture by run simulation completely. The results of different mapping show in Figure 9 as follow and find the best mapping method. The value is normalized to the first mapping method.

The x-axis is mapping sequence's permutation combination of rank, bank, and column. The first and second methods are mapping column bits to lowest. The third and fourth are rank lowest, and the others are bank-orient. This work finds the rank will get the best performance if mapping to the lowest bits. Because of each layer can work independently with low overhead rank to rank switch penalty and only shared the same TSV bus to transfer data, ranks are more parallelism than other issue the 3D design.

Bank level parallelism will not improve well in our simulation result. It may cause by opening windows constrain in rank constrain in wide I/O interface. The maximum number of row buffer be activated is two. It has to close some row buffer to open another, and the delay penalty will decrease the system performance. This work will select the following mapping sequence: "Row:Column:Bank:Rank:Channel" to evaluate our following experiment.

4.2 Adaptive Prefetching Engine

OS manage the all resources allocation in general computer architecture. The memory resource is allocated by OS and record in page table. CPU will access memory with virtual address and then convert to physical address by MMU. Memory controller must access data with physical address. Page is based on the size of block and must be the same in virtual and physical memory. Page size is normally set range size from 2 to 8KB. The same application will be allocated to continuous virtual address but it will be mapping to discrete physical block. Because programs have spatial locality, the nearly address may appear soon. This behavior is the same in physical page block. This thesis analyzes the behavior in physical block and prefetch data to improve performance. Our mechanism is much different from other that this work not focus on core level prediction but physical behavior to find memory intensive block.

TSV technology can stack different fabrication process and design more flexible. With three-dimension integration memory layers stacked on top of logic memory control layer. Memory and CPU can design independently and optimal by themselves. The control can be aimed at controller and dynamic adaptive with DRAM state. Prefetching is general way to improve DRAM performance and combine with core. Because the Prefetcher is separated to DRAM system, it is hard to get the current memory state and only determine by return requests' information. In order to get more power information, the LLC must add column and bypass to CPU. This mechanism will increase cache size and power consumption.

Prefetcher doesn't always improve system performance due to some reasons. First, miss-predict request will waste the memory bandwidth. Because one channel is shared by many banks, the useless prefetching request will block the TSV bus and delay demand requests. The extra fetch data will affect the system behavior for example access other row buffer. For some critical example, the prefetching mechanism will degrade memory system performance a lot. Second, extra prefetch request will replace original data in cache. The may cause extra cache miss and is call cache pollution. In order to prevent those drawbacks,

our prefetching will combine with controller and depend on memory rank state. This work also adds an extra cache for our prefetch requests in the 3D memory logic layer.

4.2.1 Prefetching Reference Table

There is address spatial locality property when memory access. Although virtual address translates to physical with discrete mapping, the same virtual memory block will be mapping to the same physical block. With the memory intensive access program, the continuous address would likely access soon with regular address interval. In this case, memory access pattern will probability to predict the next memory address. On the other hand, Memory non-intensive programs will hard to predict with memory analysis.

In order to distinguish memory intensive blocks, there is a cache table to record the memory block utilization. The address is based on the block numbers to record the access status. The access in the block are using an accuracy counter to reflect the continuously access in a restrict region. This thesis selects partial bits in physical address as our tag and index as Figure 10 illustrate. For example, if block size is 4KB with 8GB memory system, the address has to shift right it mean there are total 2M blocks which size is $\log_2 4K$ in our system. In order to reduce extra cost for record all 2M entry block, this work use a cache table to store partial of the 2M blocks status with most recently used.

Figure 10Prefetching Table

4.2.2 Adaptive-Prefetching Control

In order to reduce useless prefetch requests, the control will not only reference the prefetching table but collocation with rank state restriction. Our prefetching control flow is show in Figure 11**.**

First, this work adaptives the prefetch degree depend on the accuracy in reference. There is a threshold to restrict the Prefetcher. If the counter higher than threshold, the different prefetching degree is depend on the accuracy counter. Second, many researches show the prefetch requests will more likely useless if the request is delay for a long time. In our design, the prefetch request will insert depend on the command queue entry size. If the command buffer is already has many requests, prefetch request will be delayed because it has to process previous request no matter in FCFS property scheduling or demand first priority based scheduling. In other word, prefetch requests will access data and waiting for a long time. The advantage of prefetching mechanism will decrease. To prevent this case, our prefetch engine will view the number of request in command queue to decide whether insert prefetching request or not.

Memory Stacked will improve the system performance and change the memory property when TSV technology matures. With 3D architecture, there is some opportunity to optimize the overall system. For example, controller can continuously issue command to each rank because zero rank to rank switch delay. The rank switch overhead will become small than before. Continue access different layers data in 3D memory use the same TSV bus. Memory controllers have to determine which rank can transfer data. Data will delay many cycles because wide I/O is burst orient and single data rate interface. Once,

controllers lock the TSV bus, it will release many cycles decide by the data burst length. In other word, next data command will be delay by previous request because the TSV bus resource is not release yet. In those waiting cycle, other ranks will have opportunity to issue command and the delay will be overlapped.

FR-FCFS is the most popular scheduling for the DRAM memory system now. It schedules ready request first and promote the row buffer hit ratio. Most research is based on this algorithm to improve in case study. The scheduling is not optimized for 3D stacked memory when the rank to rank switch penalty disappears.

Figure 12Timing Diagram for Hide Latency Scheduling

Figure 12(a) show the case when continue issue data accessing commands to different rank. In this case, R0 issue first and R1 after it immediately. The TSV data bus will become bottleneck and R1 data has to wait for R0 transfer complete. Figure 12(b) is optimized for this situation. As soon as data access command will be served, there is an opportunity to issue commands to those not use data bus because the next data will wait for controller release the lock.

In order to improve the performance, Memory controllers can previous precharge the row buffer when the bus is busy. This work uses a counter which is call BLCD(Bus Length Counter Down) to express data utilization and exist in each bank. Whenever controllers server a request, the BLCD will increase number of burst length. BLCD counter will count down every cycle until zero.

Our algorithm will get those requests which not use data bus higher priority when the periods of data transferring delay. To reduce miss predict close page probability, there is a table to record the last row access status recently. The precharge table provides previous row access information. When a new row is activated, controller will search precharge table and load value into row predict counter.

"Row prediction counter" store last row access times. The other counter is called access counter, it will use 4 bit saturating counter and express current row access times. If row access counter is larger than row predict counter, the row will probability close soon. Predict close row buffer will bring some advantage. First, command issue when TSV bus is busy and hide precharge latency as show in Figure 12. Second, predict close row buffer will save power because the activated row buffers will cause more power consumption than close buffer. Open page policy will hold data until the precharge command issue. In other word, more power waste because recharge comes too late.

Looking for the BLCD to determine whether issue precharge or not. If the BLCD is not equal to zero, the row predict counter will compare to access counter. When the row predict counter is bigger the precharge will issue to rank, or it will follow original schedule to issue command. The control flow is described in Figure 14.

Figure 14Bank Precharge Prediction Scheduling Flow

V. Experimental Results

5.1 Environment Setup

5.1.1 System Configuration

AMILIA

Table 4 System Configuration

This work uses GEM5 which is a full system simulator to get the memory traces. Our target is 8 cores with private L1 caches and shared L2 cache architecture. Table5 show our target simulator environment. The memory trace information include timestamp and physical memory address are generated by running benchmark on GEM5. This thesis evaluate the DRAM system with parsec**[20]** and spec2006**[21]** benchmark which supplies parallel program and memory intensive workload. The detail benchmark is show detail in table 6.

Table 5 Overview of Benchmark

The memory configuration is described our memory system timgin constrain parameter. The timing parameter is reference by wide I/O specific from JEDEC and show in table 6.

Table 6 Memory Configuration

5.1.2 Power Model

Wide I/O interface is a new technology and not release physical specific with product yet. This work selects LPDDR2 as reference target because its property is close to Wide I/O. Our power parameter reference Micron LPDDR2 to analysis new design in trend. The power formula is voltage multiple current. There are two voltages support in LPDDR2: VDD1 is set to 1.8V and VDD2 is set to 1.2V. The current multiple correspond voltage and accumulate when following status occur. If controller issue some commands the action power will be accumulated. Otherwise, background calculates DRAM idle power and different from DRAM power mode and row buffer status. Table 8 shows LPDDR2 power parameter.

Table 7 LPDDR2 Power Parameter

5.2 Precharge Prediction Analysis

Because some compoments of our control mechanism is an extra overhead, this thesis takes not only performance but also hardware cost overhead into consider. The extra precharge mechanism in our design using a precharge prediction table to record the row status and show in Figure 15.

Figure 15Precharge Prediction Table Size

The x-axis is the number of table entries and the y-axis is improvement percentage by original. The average line is increasing rapidly before the table entries is 16. It grows slowly and saturation when the number is greater than 16 because the buffer will not change row frequently in a period. It may be caused by RLP-oriented address mapping and FR-FCFS based scheduling. It seems to when 16 entries is most efficiency.

Figure 17Power Improvement by different Scheduling

Figure 16 show the latency in our Latency overlapping scheduling by precharge prediction and compare to the MLP scheduling. MLP scheduling separate read/write in different command queues and issue write command only when the number of write exceed threshold. Our method is less than MLP scheduling by improvement latency because MLP save not only read to write timing delay but prioritizes the read command. Figure 17 show our method can help to save power because pre-close row buffer can use lower current and more power efficiency. Because our scheduling is control those precharge command in bus busy slot, it's independently with MLP scheduling. The result shows our method can combine MLP scheduling without conflict.

5.3 Adaptive-Prefetch Analysis

Figure 18Prefetching Caching Size Tradeoff

Figure 18 shows our analysis about prefetch cache size. The x-axis is the number of table entries and the y-axis is memory improvement by original version. Because each entry size is up to 64B to store full cache block data. The prefetch cache size will increase rapidly if the cache extend. In our analysis, when table is larger than 128 entries, the performance will improve slowly but double the cache size because the prefetch requests not replacement so frequently and the size is enough. This work selects 128 as prefetch cache entries.

Figure 19 Improvement Relative to No Threshold Prefetching

In order to reduce useless prefetch request and improve rank level parallelism, this work proposes constrain the number of prefetch requests when the command buffer exist requests more than a threshold. This method not only helps to reduce useless prefetch requests but also rank balance. Figure 19 indicates threshold is set to quarter of command queue depth.

Figure 21Latency Improvements by Adaptive-Prefetching

Figure 22DRAM Power Overhead by Adaptive-Prefetching Technology

Figure 21 show our adaptive-prefetching mechanism performance improvement of DRAM latency. It will improve nearly 11.7% in average. Our control will limit prefetch requests so the performance is also limited. Figure 11 show the extra energy overhead. Although prefetch mechanism can reduce latency, useless data will cause extra power consumption. The power cost more 3.68% with our prefetcher.

5.4 Hardware Cost

Table 8 Precharge Predict Overhead

Table 8 show the hardware overhead of latency overlapping scheduling implement. Because the precharge predition table is exist in each bank. The table size has to multiple to

number of bank.

Table 9 Adaptive-Prefetch Overhead

Table 9 show the cost for Prefetching mechanism and cache. Because the prefetcher and cache exist in each channel controller. The table size has to multiple to number of channel.

VI. Conclusion

This thesis provides an ESL platform with TSV architecture that can support wide I/O interface. Our simulator is modularize with configurable design parameters so it's ease to model different architecture. This work also speedup the simulation time by using pthread acceleration method for each channel. The speedup is approximate 3.1 times with four channel controller design relative to sequential version.

With analysis of different memory mapping methods in wide I/O, results show that rank level parallelsim is good for 3D design because the rank to rank switch penalty decreases and the maximum number of activated windows is constrained.

Finally, this work proposes two mechanisms to improve system performance. Adaptive prefetching techniques analyzes memory intensiveness and access locality to prefetch data and considers the number of rank command to improve latency nearly by 13% with 3.5% power overhead. Latency overlapping schedules ahead of precharge command by overlapping TSV data transfer delay. Latency overlapping scheduling helps to reduce 0.6% latency and save 4% power consumption by pre closing row buffers.

The hardware cost is an extra overhead in design. This work tradeoff overhead to get the proper hardware size. The result shows our mechanism is cost efficienct.

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